Specifications Drawing

PCB # 3004-Rev B - 500MHz ADC Board

6/7/2023

Notes:
1. Material - Magnetics
2. Electroless Nickel Immersion Gold Plating: min 25um Au, 2.5-5um Ni, 0.05-0.2um Au
3. Vias in pad must be filled with solid fills, plumb and plated over
4. 1 oz Cu on Top, Bottom, and internal planes. 0.5oz Cu on internal Signal Layers
5. Controlled Impedance: 50Ohm - single ended, 900Ohm - Differential
6. Board Thickness: 0.065" +/- 0.002"
7. Minimum Trace Width/Clearance: 0.1mil
8. Remove all non-functional inner layer pads for pins and vias
9. 45 Degree Chamfer
10. Mill 2.5mm on two edges of the board, on bottom side only, to a remaining thickness of 0.07" +/- 0.002"